


APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	[METHOD OF FABRICATING FLIP CHIP BALL GRID ARRAY PACKAGE]		
Application Type : regular, utility Attorney Docket Number : 11182-US-PA			
Correspondence address: Customer Number: 31561 			
Priority Data: Doc.No: 92119938; Country -TW ; Date: 2003-07-22 us-priority-claimed			
Inventor Information: <u>Inventor 1:</u> Applicant Authority Type: Inventor Citizenship: TW Name prefix: Mr. Given Name: Meng-Jen Family Name: Wang Residence: City of Residence: Pingtung Country of Residence: TW Address-1 of Mailing Address: No. 68, Heping Rd., Pingtung City, Address-2 of Mailing Address: City of Mailing Address: Pingtung State of Mailing Address: Postal Code of Mailing Address: 900 Country of Mailing Address: TW Phone: Fax: E-mail:			
Attorney Information: practitioner(s) at Customer Number:			

31561



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